

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Ming-Chi LIAW et al. : Group Art Unit: Unassigned
Continuation Application of: : Examiner: Unassigned
Application S.N. 09/155,181 :
Filed: March 26, 1999 :
Continuation Application Filed: :
17 July 2003 :

For: SOLUTIONS AND PROCESSES FOR REMOVAL OF SIDEWALL
RESIDUE AFTER DRY ETCHING

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SIR:

Please amend the above identified application as indicated below prior to
examination.

IN THE CLAIMS

Please cancel claims 1-12 without prejudice or disclaimer.

Please add the following new claims:

13. A process for removing photoresist after drywall etching comprising treating a wafer after dry etching with a solution comprising sulfuric acid and a mixture of a fluorine containing compound and hydrogen peroxide.